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ABSTRACT

APPARATUS AND METHOD FOR MULTIPLE SUBSTRATE PROCESSING

A system for cutting a plurality of substrates of integrated circuit units comprising a plurality of tables, each table including a plurality of trays, each tray arranged to receive one of said substrates; each of said tables selectively movable between a respective loading station for receiving said substrates and a cutting station for cutting the substrates, and; a substrate placement device for placing the substrates on the respective trays of said tables; wherein the substrate placement device is arranged to sequentially place substrates on said tables with said tables arranged to sequentially move to the cutting station after receiving the substrates and then return to their respective loading stations for placement of additional substrates.

Fig 1